NCC AVS PAG-TFUG

Joint Users Group Meeting

Thursday, September 10, 2015, 12:30 - 5pm

**Semiconductor Technology beyond 7nm**

Sponsored by:  Kurt J. Lesker Company

Time:                    Free Lunch 12:30pm,

                        Talks beginning at 1:00PM

Co-Chairs:

Chakku Gopalan, Adesto Technologies, [Chakku.gopalan@adesotech.com](mailto:Chakku.gopalan@adesotech.com)

Roman Mostovoy, Applied Materials, [Roman\_Mostovoy@amat.com](mailto:Roman_Mostovoy@amat.com)

Michael Oye, UC Santa Cruz, [moye@ucsc.edu](mailto:moye@ucsc.edu)

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Jeffrey Shields, Adesto Technologies, [Jeffrey.Shields@att.net](mailto:Jeffrey.Shields@att.net)

1. **Carbon-based Materials for Flexible Electronics, Nan Liu; Zhenan Bao, Stanford University**

1. **Zeiss Process Gas Analyzer based on Ion Trap Technology, Outstanding Performances as In-line, Real Time Gas Analyzer, Michel Aliman, Hin Yiu Anthony Chung , Martin Antoni, Gennady Fedosenko, Alexander Laue, Rüdiger Reuter, Valerie Derpmann, Leonid Gorkhover, Andreas Gorus, Andreas Pecher Carl Zeiss SMT GmbH, Rudolf-Eber-Str. 22, 73447 Oberkochen, Germany**

1. **Energy-efficient Design for Emerging NVM Technology: Enabled by Carbon Nano-materials, Ethan C. Ahn, Ph.D., Department of Electrical Engineering, Stanford Nanoelectronics Lab., Stanford University, Stanford, CA 94305, E-mail:**[**cyahn@stanford.edu**](mailto:cyahn@stanford.edu)
2. **Limitations and Challenges to Meet Moore's Law,Sung Kim, Sr. Director of Maydan Technology Center; Advanced Products Technology Development, Applied Materials.**
3. **Sub-5 nm Patterning and Applications by Nanoimprint Lithography and Helium Ion Beam Lithography *Yuanrui Li[1], Ahmed Abbas[1], Yuhan Yao[1], Yifei Wang[1], Wen-Di Li[2], Chongwu Zhou[1] and Wei Wu[1]\* email:***[***wu.w@usc.edu***](mailto:wu.w@usc.edu)